

NUD3124

Automotive Inductive Load Driver

This MicroIntegration™ part provides a single component solution to switch inductive loads such as relays, solenoids, and small DC motors without the need of a free-wheeling diode. It accepts logic level inputs, thus allowing it to be driven by a large variety of devices including logic gates, inverters, and microcontrollers.

Features

- Provides Robust Interface between D.C. Relay Coils and Sensitive Logic
- Capable of Driving Relay Coils Rated up to 150 mA at 12 Volts
- Replaces 3 or 4 Discrete Components for Lower Cost
- Internal Zener Eliminates Need for Free-Wheeling Diode
- Meets Load Dump and other Automotive Specs
- Pb-Free Packages are Available

Typical Applications

- Automotive and Industrial Environment
- Drives Window, Latch, Door, and Antenna Relays

Benefits

- Reduced PCB Space
- Standardized Driver for Wide Range of Relays
- Simplifies Circuit Design and PCB Layout
- Compliance with Automotive Specifications



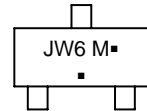
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<http://onsemi.com>

MARKING DIAGRAMS



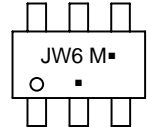
**SOT-23
CASE 318
STYLE 21**



JW6 = Specific Device Code
M = Date Code
▪ = Pb-Free Package
(Note: Microdot may be in either location)



**SC-74
CASE 318F
STYLE 7**



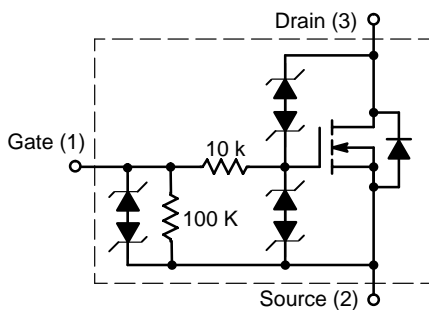
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ORDERING INFORMATION

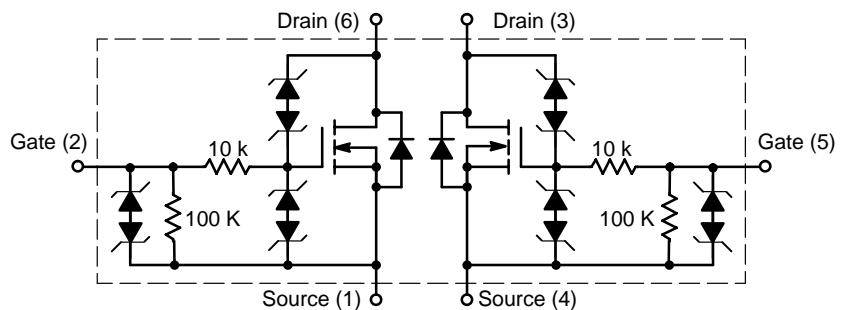
Device	Package	Shipping†
NUD3124LT1	SOT-23	3000/Tape & Reel
NUD3124LT1G	SOT-23 (Pb-Free)	3000/Tape & Reel
NUD3124DMT1	SC-74	3000/Tape & Reel
NUD3124DMT1G	SC-74 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

INTERNAL CIRCUIT DIAGRAMS



CASE 318



CASE 318F

NUD3124

MAXIMUM RATINGS (T_J = 25°C unless otherwise specified)

Symbol	Rating	Value	Unit
V _{DSS}	Drain-to-Source Voltage – Continuous (T _J = 125°C)	28	V
V _{GSS}	Gate-to-Source Voltage – Continuous (T _J = 125°C)	12	V
I _D	Drain Current – Continuous (T _J = 125°C)	150	mA
E _Z	Single Pulse Drain-to-Source Avalanche Energy (For Relay's Coils/Inductive Loads of 80 Ω or Higher) (T _J Initial = 85°C)	250	mJ
P _{PK}	Peak Power Dissipation, Drain-to-Source (Notes 1 and 2) (T _J Initial = 85°C)	20	W
E _{LD1}	Load Dump Suppressed Pulse, Drain-to-Source (Notes 3 and 4) (Suppressed Waveform: V _s = 45 V, R _{SOURCE} = 0.5 Ω, T = 200 ms) (For Relay's Coils/Inductive Loads of 80 Ω or Higher) (T _J Initial = 85°C)	80	V
E _{LD2}	Inductive Switching Transient 1, Drain-to-Source (Waveform: R _{SOURCE} = 10 Ω, T = 2.0 ms) (For Relay's Coils/Inductive Loads of 80 Ω or Higher) (T _J Initial = 85°C)	100	V
E _{LD3}	Inductive Switching Transient 2, Drain-to-Source (Waveform: R _{SOURCE} = 4.0 Ω, T = 50 μs) (For Relay's Coils/Inductive Loads of 80 Ω or Higher) (T _J Initial = 85°C)	300	V
Rev-Bat	Reverse Battery, 10 Minutes (Drain-to-Source) (For Relay's Coils/Inductive Loads of 80 Ω or more)	-14	V
Dual-Volt	Dual Voltage Jump Start, 10 Minutes (Drain-to-Source)	28	V
ESD	Human Body Model (HBM) According to EIA/JESD22/A114 Specification	2,000	V

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Nonrepetitive current square pulse 1.0 ms duration.
2. For different square pulse durations, see Figure 2.
3. Nonrepetitive load dump suppressed pulse per Figure 3.
4. For relay's coils/inductive loads higher than 80 Ω, see Figure 4.

THERMAL CHARACTERISTICS

Symbol	Rating	Value	Unit	
T _A	Operating Ambient Temperature	-40 to 125	°C	
T _J	Maximum Junction Temperature	150	°C	
T _{STG}	Storage Temperature Range	-65 to 150	°C	
P _D	Total Power Dissipation (Note 5) Derating above 25°C	SOT-23	225	mW
			1.8	mW/°C
P _D	Total Power Dissipation (Note 5) Derating above 25°C	SC-74	380	mW
			3.0	mW/°C
R _{θJA}	Thermal Resistance Junction-to-Ambient (Note 5)	SOT-23	556	°C/W
		SC-74	329	

5. Mounted onto minimum pad board.

NUD3124

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Drain to Source Sustaining Voltage (I _D = 10 mA)	V _{BRDSS}	28	34	38	V
Drain to Source Leakage Current (V _{DS} = 12 V, V _{GS} = 0 V) (V _{DS} = 12 V, V _{GS} = 0 V, T _J = 125°C) (V _{DS} = 28 V, V _{GS} = 0 V) (V _{DS} = 28 V, V _{GS} = 0 V, T _J = 125°C)	I _{DSS}	–	–	0.5 1.0 50 80	μA
Gate Body Leakage Current (V _{GS} = 3.0 V, V _{DS} = 0 V) (V _{GS} = 3.0 V, V _{DS} = 0 V, T _J = 125°C) (V _{GS} = 5.0 V, V _{DS} = 0 V) (V _{GS} = 5.0 V, V _{DS} = 0 V, T _J = 125°C)	I _{GSS}	–	–	60 80 90 110	μA
ON CHARACTERISTICS					
Gate Threshold Voltage (V _{GS} = V _{DS} , I _D = 1.0 mA) (V _{GS} = V _{DS} , I _D = 1.0 mA, T _J = 125°C)	V _{GS(th)}	1.3 1.3	1.8 –	2.0 2.0	V
Drain to Source On-Resistance (I _D = 150 mA, V _{GS} = 3.0 V) (I _D = 150 mA, V _{GS} = 3.0 V, T _J = 125°C) (I _D = 150 mA, V _{GS} = 5.0 V) (I _D = 150 mA, V _{GS} = 5.0 V, T _J = 125°C)	R _{DS(on)}	–	–	1.4 1.7 0.8 1.1	Ω
Output Continuous Current (V _{DS} = 0.25 V, V _{GS} = 3.0 V) (V _{DS} = 0.25 V, V _{GS} = 3.0 V, T _J = 125°C)	I _{DS(on)}	150 140	200 –	– –	mA
Forward Transconductance (V _{DS} = 12 V, I _D = 150 mA)	g _{FS}	–	500	–	mmho
DYNAMIC CHARACTERISTICS					
Input Capacitance (V _{DS} = 12 V, V _{GS} = 0 V, f = 10 kHz)	C _{iss}	–	32	–	pf
Output Capacitance (V _{DS} = 12 V, V _{GS} = 0 V, f = 10 kHz)	C _{oss}	–	21	–	pf
Transfer Capacitance (V _{DS} = 12 V, V _{GS} = 0 V, f = 10 kHz)	C _{rss}	–	8.0	–	pf
SWITCHING CHARACTERISTICS					
Propagation Delay Times: High to Low Propagation Delay; Figure 1, (V _{DS} = 12 V, V _{GS} = 3.0 V) Low to High Propagation Delay; Figure 1, (V _{DS} = 12 V, V _{GS} = 3.0 V) High to Low Propagation Delay; Figure 1, (V _{DS} = 12 V, V _{GS} = 5.0 V) Low to High Propagation Delay; Figure 1, (V _{DS} = 12 V, V _{GS} = 5.0 V)	t _{PHL} t _{PLH} t _{PHL} t _{PLH}	– – – –	890 912 324 1280	– – – –	ns
Transition Times: Fall Time; Figure 1, (V _{DS} = 12 V, V _{GS} = 3.0 V) Rise Time; Figure 1, (V _{DS} = 12 V, V _{GS} = 3.0 V) Fall Time; Figure 1, (V _{DS} = 12 V, V _{GS} = 5.0 V) Rise Time; Figure 1, (V _{DS} = 12 V, V _{GS} = 5.0 V)	t _f t _r t _f t _r	– – – –	2086 708 556 725	– – – –	ns

NUD3124

TYPICAL PERFORMANCE CURVES

($T_J = 25^\circ\text{C}$ unless otherwise noted)

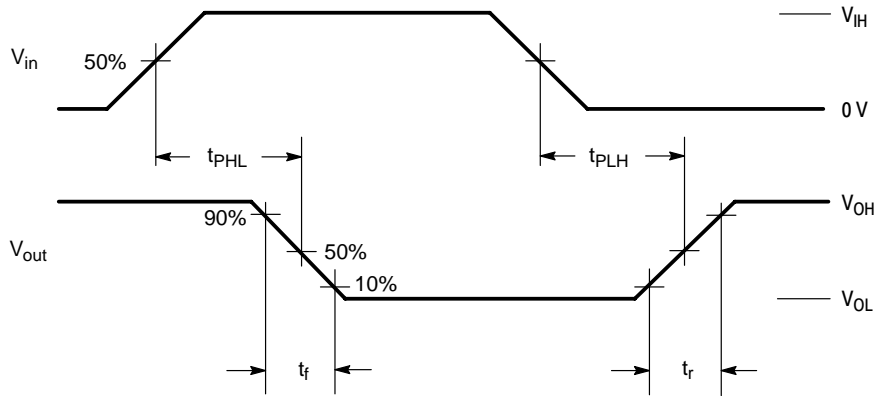


Figure 1. Switching Waveforms

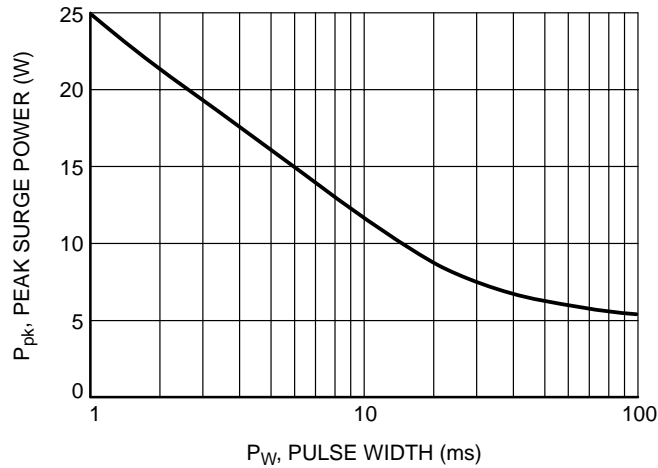


Figure 2. Maximum Non-repetitive Surge Power versus Pulse Width

Load Dump Pulse Not Suppressed:

$V_R = 13.5\text{ V Nominal } \pm 10\%$

$V_S = 60\text{ V Nominal } \pm 10\%$

$T = 300\text{ ms Nominal } \pm 10\%$

$T_R = 1 - 10\text{ ms } \pm 10\%$

Load Dump Pulse Suppressed:

NOTE: Max. Voltage DUT is exposed to is approximately 45 V.

$V_S = 30\text{ V } \pm 20\%$

$T = 150\text{ ms } \pm 20\%$

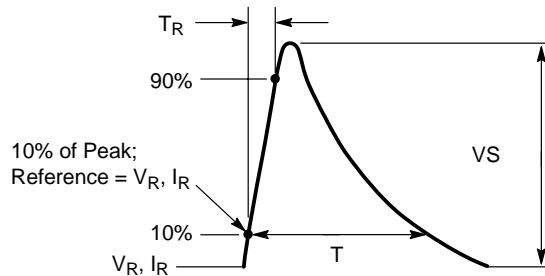


Figure 3. Load Dump Waveform Definition

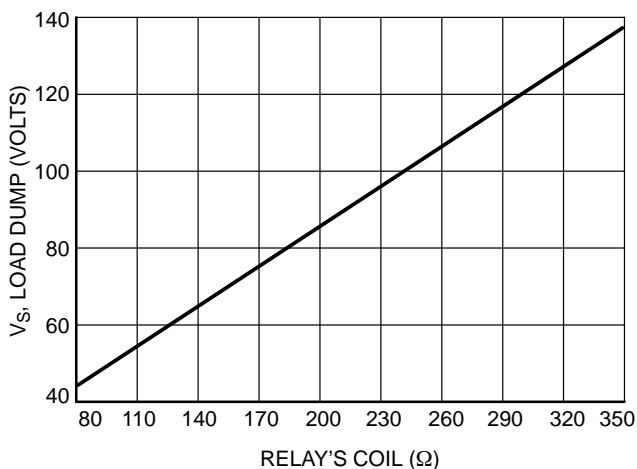


Figure 4. Load Dump Capability versus Relay's Coil dc Resistance

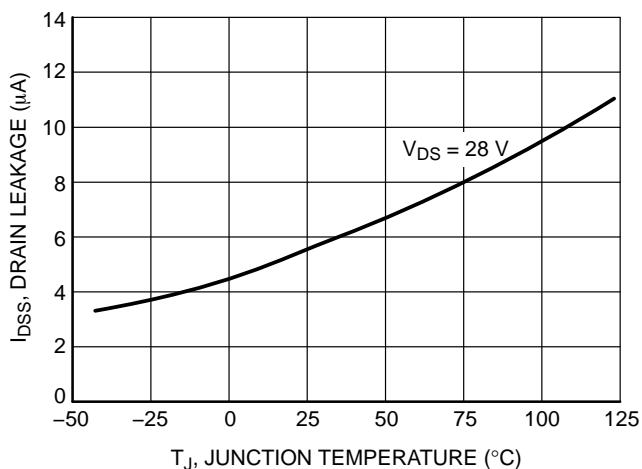


Figure 5. Drain-to-Source Leakage versus Junction Temperature

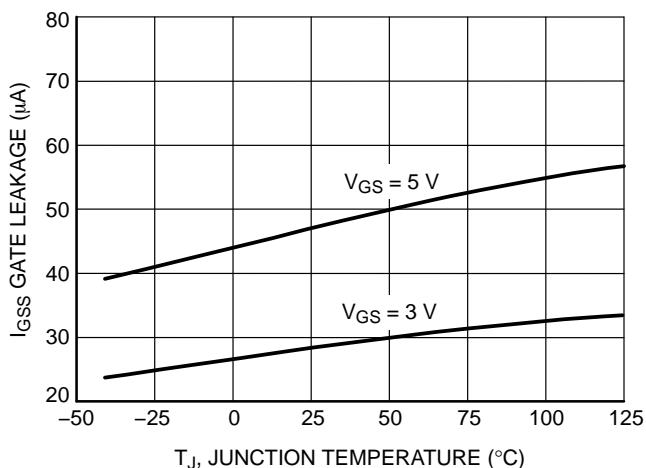


Figure 6. Gate-to-Source Leakage versus Junction Temperature

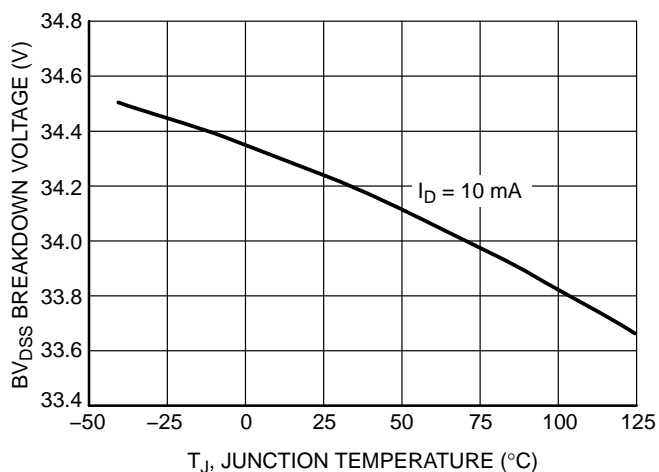


Figure 7. Breakdown Voltage versus Junction Temperature

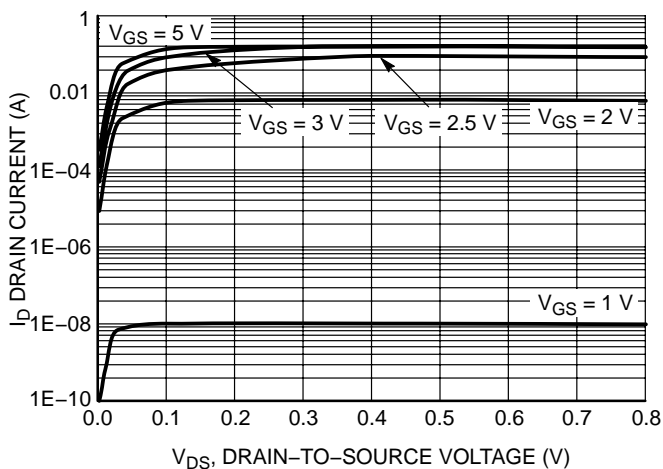


Figure 8. Output Characteristics

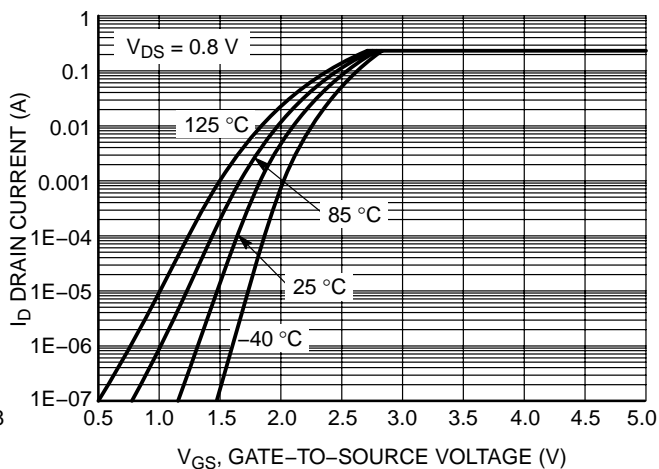


Figure 9. Transfer Function

NUD3124

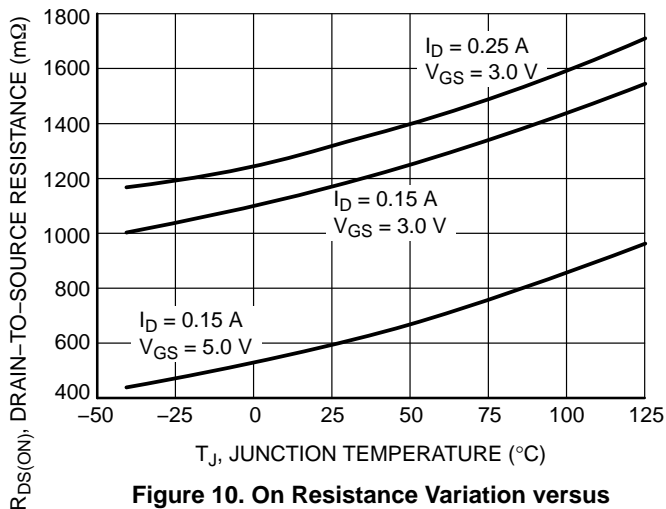


Figure 10. On Resistance Variation versus Junction Temperature

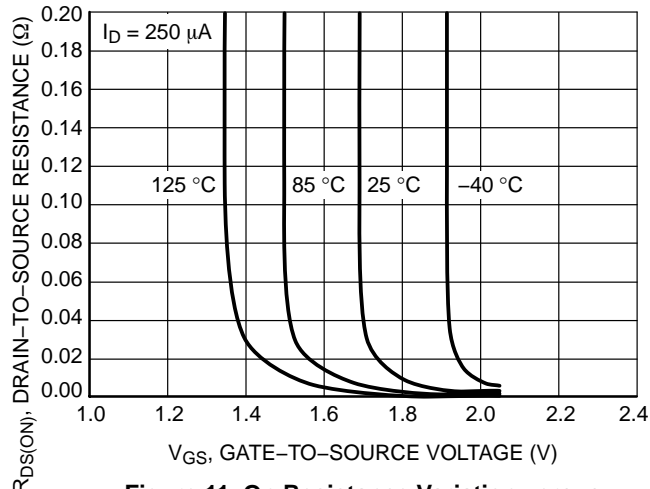


Figure 11. On Resistance Variation versus Gate-to-Source Voltage

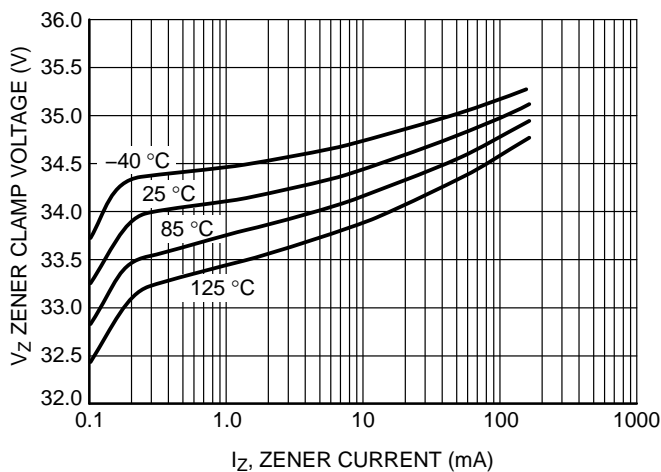


Figure 12. Zener Clamp Voltage versus Zener Current

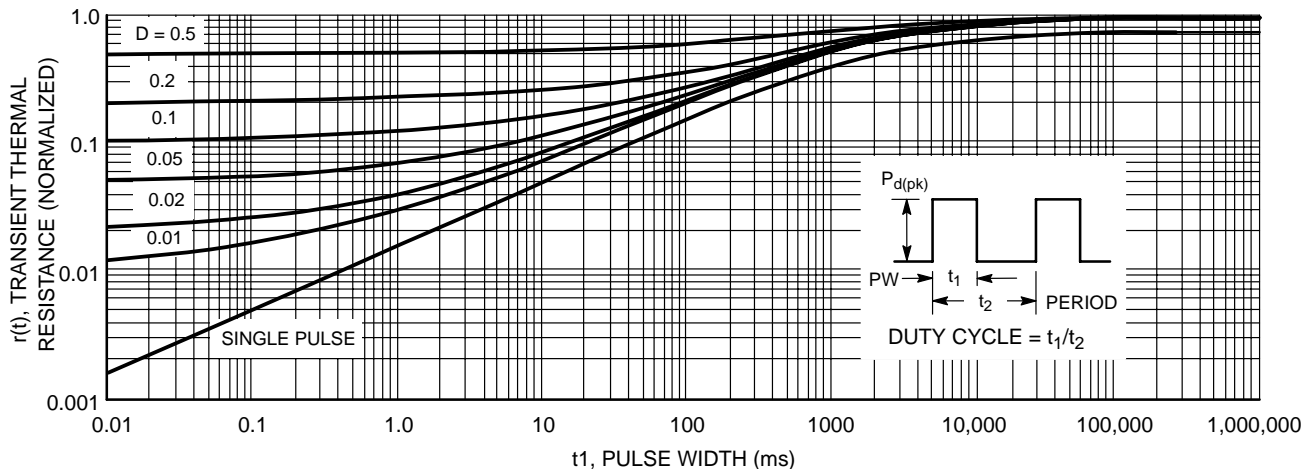


Figure 13. Transient Thermal Response for NUD3124LT1

NUD3124

APPLICATIONS INFORMATION

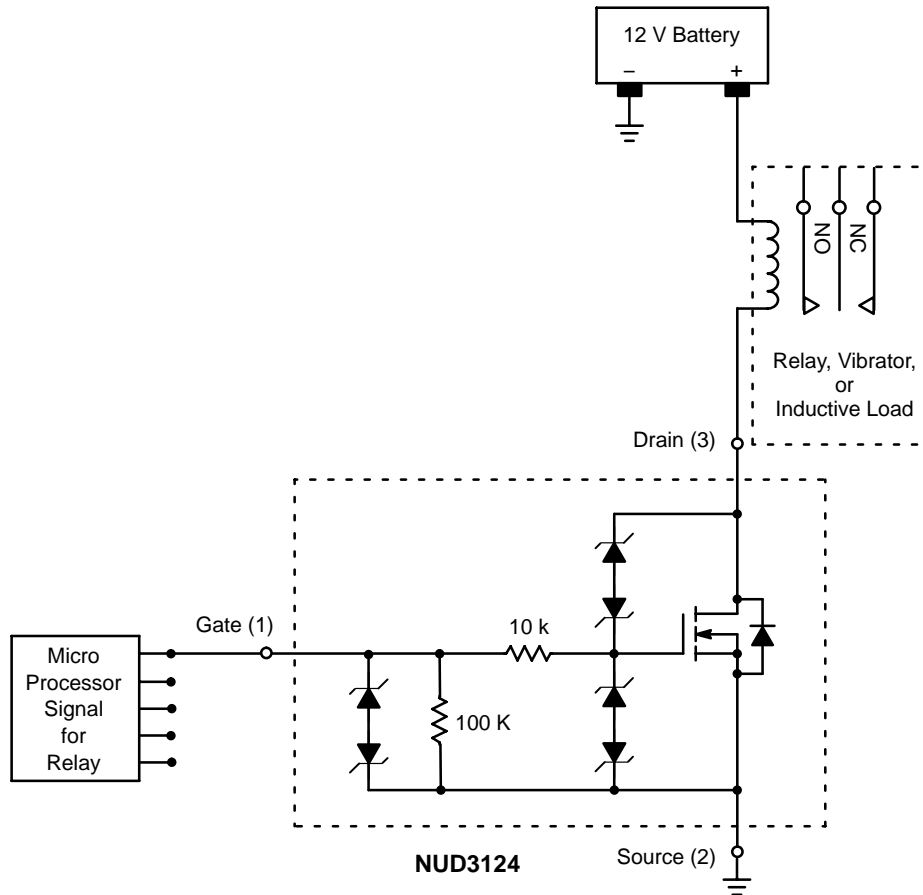
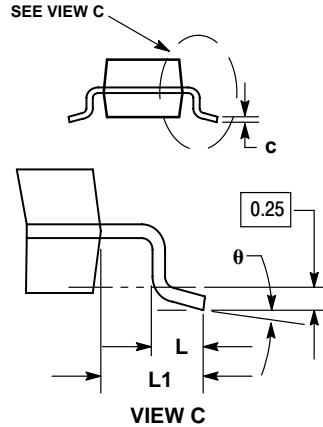
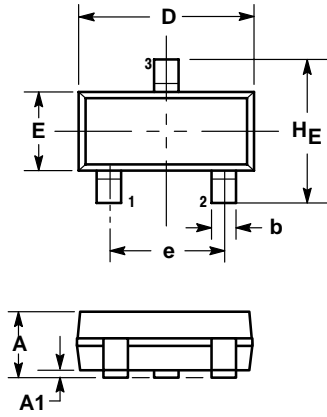


Figure 14. Applications Diagram

NUD3124

PACKAGE DIMENSIONS

SOT-23 (TO-236)
CASE 318-08
ISSUE AN

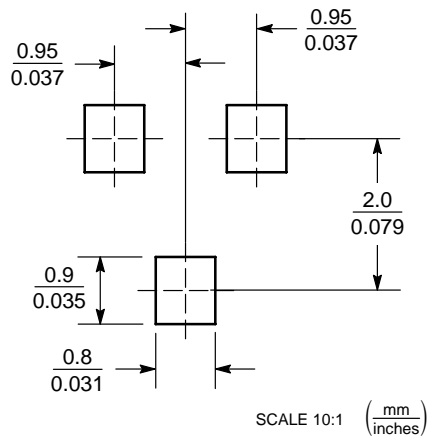


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

- STYLE 21:
PIN 1. GATE
2. SOURCE
3. DRAIN

SOLDERING FOOTPRINT*

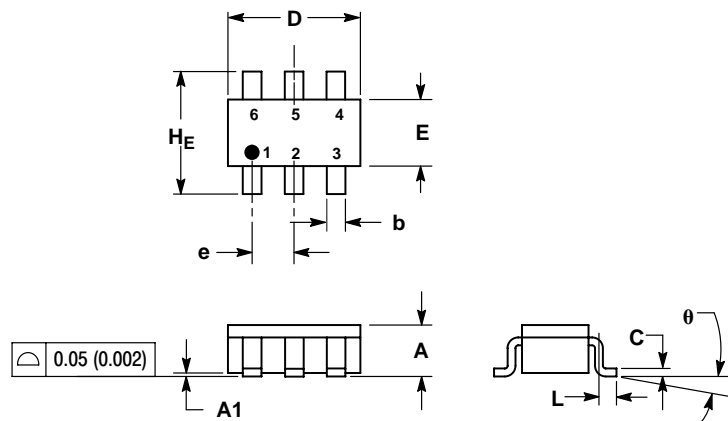


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NUD3124

PACKAGE DIMENSIONS

SC-74 CASE 318F-05 ISSUE L



NOTES:

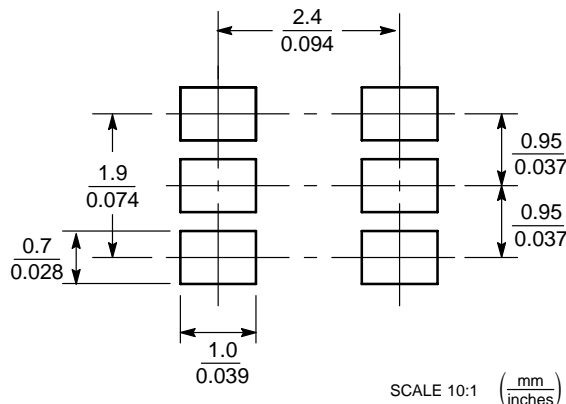
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3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 318F-01, -02, -03 OBSOLETE. NEW STANDARD 318F-04.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.90	1.00	1.10	0.035	0.039	0.043
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.25	0.37	0.50	0.010	0.015	0.020
c	0.10	0.18	0.26	0.004	0.007	0.010
D	2.90	3.00	3.10	0.114	0.118	0.122
E	1.30	1.50	1.70	0.051	0.059	0.067
e	0.85	0.95	1.05	0.034	0.037	0.041
L	0.20	0.40	0.60	0.008	0.016	0.024
HE	2.50	2.75	3.00	0.099	0.108	0.118
theta	0°	-	10°	0°	-	10°

STYLE 7:

- PIN 1. SOURCE 1
- GATE 1
- DRAIN 2
- SOURCE 2
- GATE 2
- DRAIN 1

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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